

Supposed PFAS materials at Swissbit Germany AG:

Line	Material	Ingredients	Usage	Description	PFAS content
1	Chip adhesive	Perfluoropolyoxyalkane ether~	Adhesive	Chip bonding	confirmed
2	Die Adhesive Film (DAF)	m-tolylidene diisocyanate silicon dioxide	Adhesive	Chip bonding	supposed
3	Dam&Fill potting	Siloxanes and Silicones, 3,3,3-methyl trifluoropropyl	Encapsulation	Chip encapsulation material	confirmed
4	Mold compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-diyl)-bis(oxymethylen))bisoxiran 2,2'-(methylenebis((6-dimethyl-4,1-phenylene)oxymethylene))bis oxirane Polycondensate of 4,4'-bis(methoxymethyl)biphenyl and phenol Silica, vitreous	Encapsulation	MAP Mold Material	supposed
5	Flux Remover	Methyl-nonafluorbutylether (Methyl Nonafluorobutyl Ether) Methyl-nonafluorisobutylether (Methyl Nonafluoroisobutyl Ether) trans-dichloroethylene	Flux	PCB Repair	supposed
6	Flux	Dipotassium tetraborate tetrahydrate potassium fluoride potassium tetrafluoroborate silicon dioxide	Flux	Flux for electr. Test construction work	supposed
7	Grease	disodium sebacate Ethene, 1,1,2,2- tetrafluoro-, homopolymer	Lubricant	Heat resistant grease for mold equipment	supposed
8	Mold Release Film	ETFE	Mold Foil	Top Foil for Mold Release	supposed
9	Substrate (PCB)	no info	PCB	Package substrate	supposed
10	Chip underfiller	Siloxanes and Silicones, 3,3,3-methyl trifluoropropyl	Underfill	Chip or package underfill	confirmed
11	Vacuum Oil	1-propene, 1,1,2,3,3,3-hexafluoro-, oxidized, polymd.	Vacuumöl	Vacuum oil for plasma processing	supposed